materials

MDPI

Supplementary Materials

Formation and Growth of Intermetallic Compounds during Reactions between Liquid Gallium and Solid Nickel

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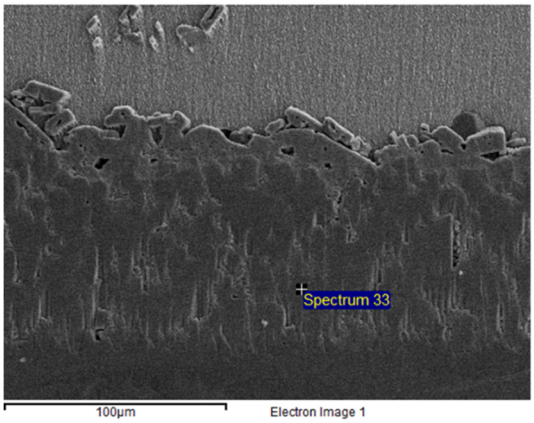
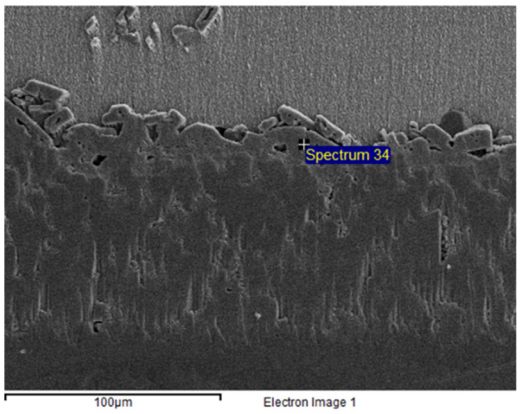
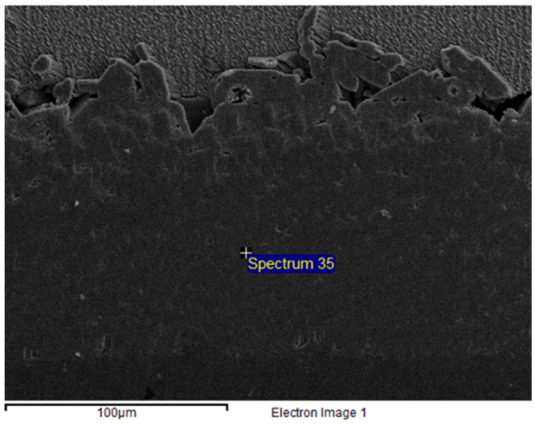


Element	Weight%	Atomic%
Ni K	29.65	33.36
Ga L	70.35	66.64
Totals	100.00	

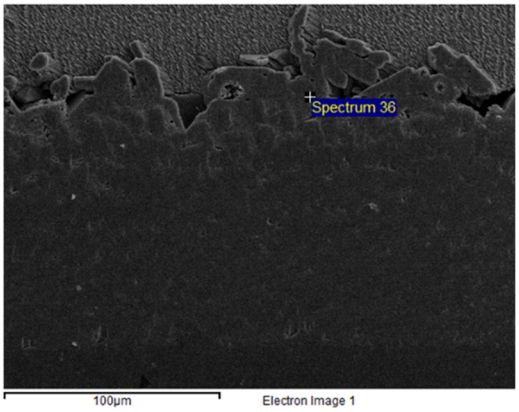


Element	Weight%	Atomic%
Ni K	9.33	10.89
Ga L	90.67	89.11
Totals	100.00	

Figure S1. EDX analysis of the interfacial IMCs in the specimen reacted at 300 °C for 180 min.

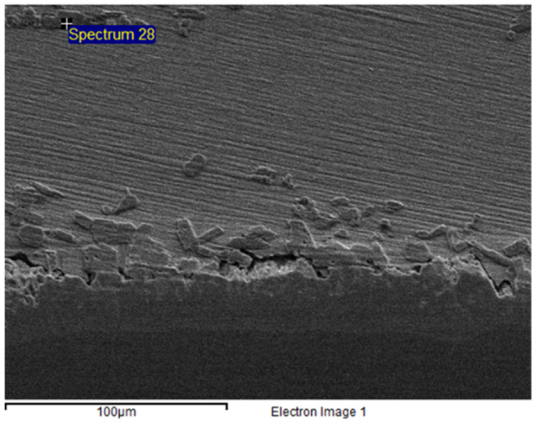


Element	Weight%	Atomic%
Ni K	26.79	30.29
Ga L	73.21	69.71
Totals	100.00	

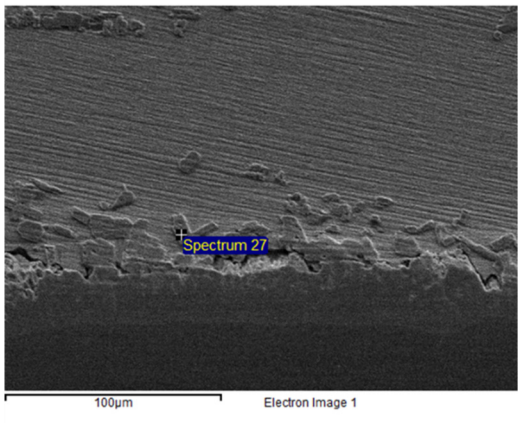


Element	Weight%	Atomic%
Ni K	4.23	4.99
Ga L	95.77	95.01
Totals	100.00	

Figure S2. EDX analysis of the interfacial IMCs in the specimen reacted at 300 °C for 240 min.

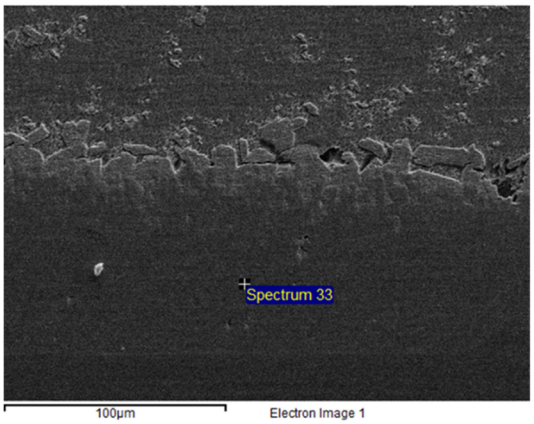


Element	Weight%	Atomic%
Ni K	6.79	7.96
Ga L	93.21	92.04
Totals	100.00	

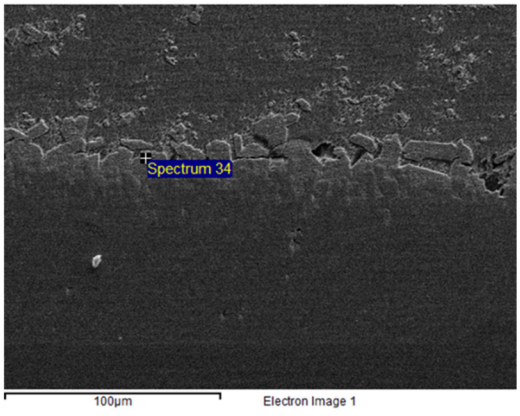


Element	Weight%	Atomic%
Ni K	6.32	7.42
Ga L	93.68	92.58
Totals	100.00	

Figure S3. EDX analysis of the interfacial IMCs in the specimen reacted at 350 °C for 60 min.



Element	Weight%	Atomic%
Ni K	25.65	29.06
Ga L	74.35	70.94
Totals	100.00	



Element	Weight%	Atomic%
Ni K	8.23	9.62
Ga L	91.77	90.38
Totals	100.00	

Figure S4. EDX analysis of the interfacial IMCs in the specimen reacted at 350 °C for 240 min.